


Notes: (Unless Otherwise Specified).

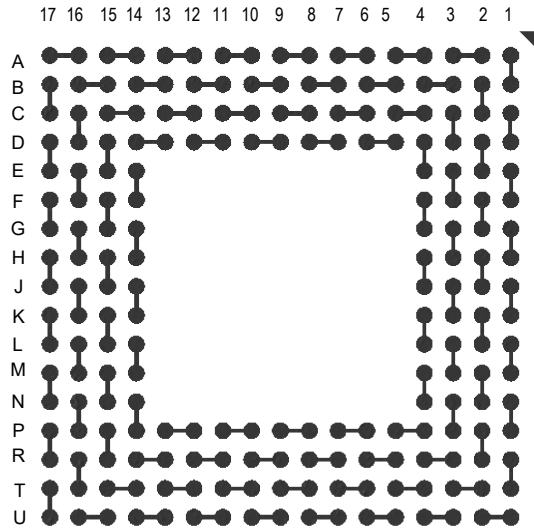
- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
- 3) BALL DIAMETER (BEFORE REFLOW): 0.76mm (30 MIL).
- 4) SOLDER MASK DEFINED PAD OPENING: 0.635mm (25 MIL).
- 5) PAD Cu DIAMETER: 0.762mm (30 MIL).
- 6) SUBSTRATE MATERIAL: BT.
- 7) DUMMY DIE IS OPTIONAL.
- 8) DAISY CHAIN PATTERN (SEE PAGE 2).
- 9) MSL-3 RECOMMENDED BAKING 24 HOURS @ 125°C TO REMOVE MOISTURE PRIOR SOLDERING TO PC BOARD.

PART NUMBER TABLE

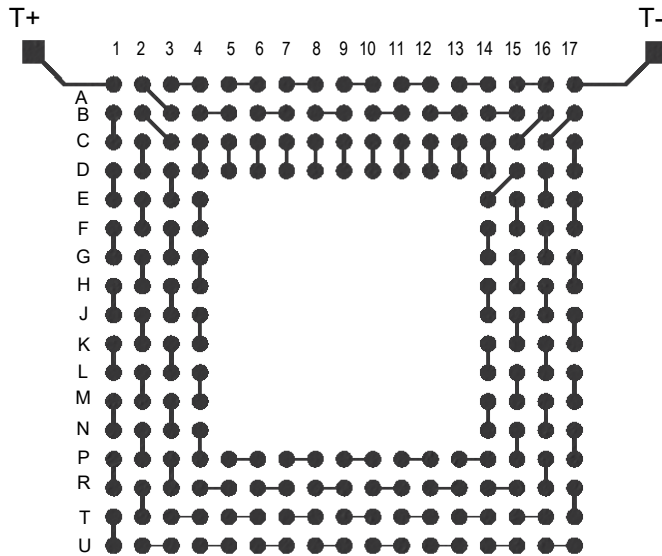
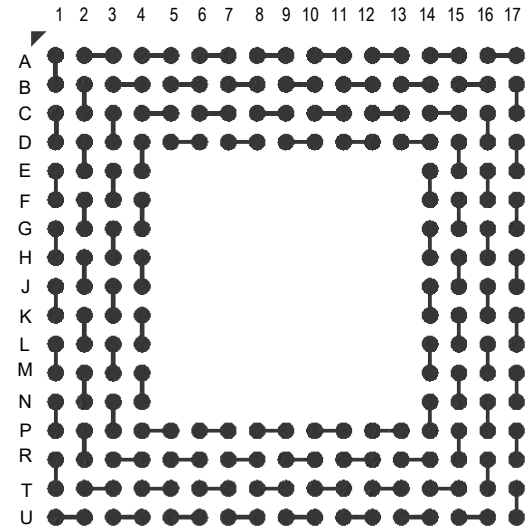
PART NUMBER	BALL ALLOY	Pb-Free	RoHS	Si DIE
BGA208T1.27C-DC170D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES
BGA208T1.27-DC170D	Sn63/Pb37	NO	NO	YES

APPROVALS		DATE				
DRAWN	T.Au	6/23/2021				
ENG	M. Hart	6/23/2021	TITLE		BGA208T1.27C-DC170D DAISY CHAIN DUMMY	
MFG			SCALE		SIZE	DRAWING NO.
QA			3:1		A	521704
CUST						REV A
REVISED			DO NOT SCALE DRAWING			SHEET 1 OF 3

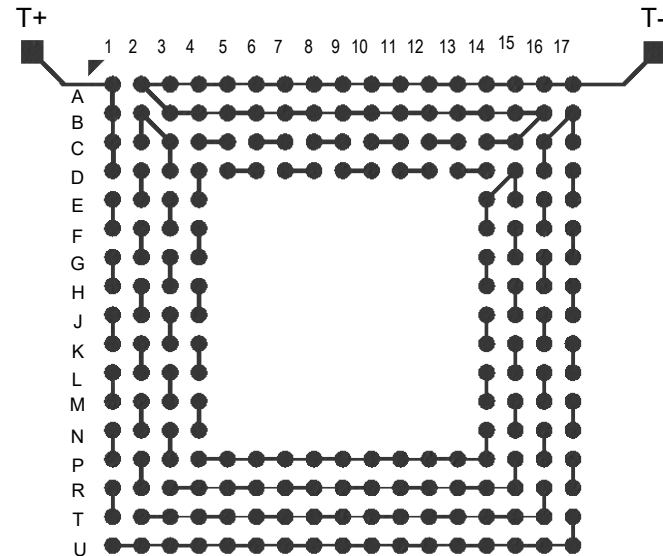
BALL VIEW



BOTTOM SIDE (TOP X-RAY VIEW)



TEST VEHICLE BOARD



AFTER MOUNT

Notes:

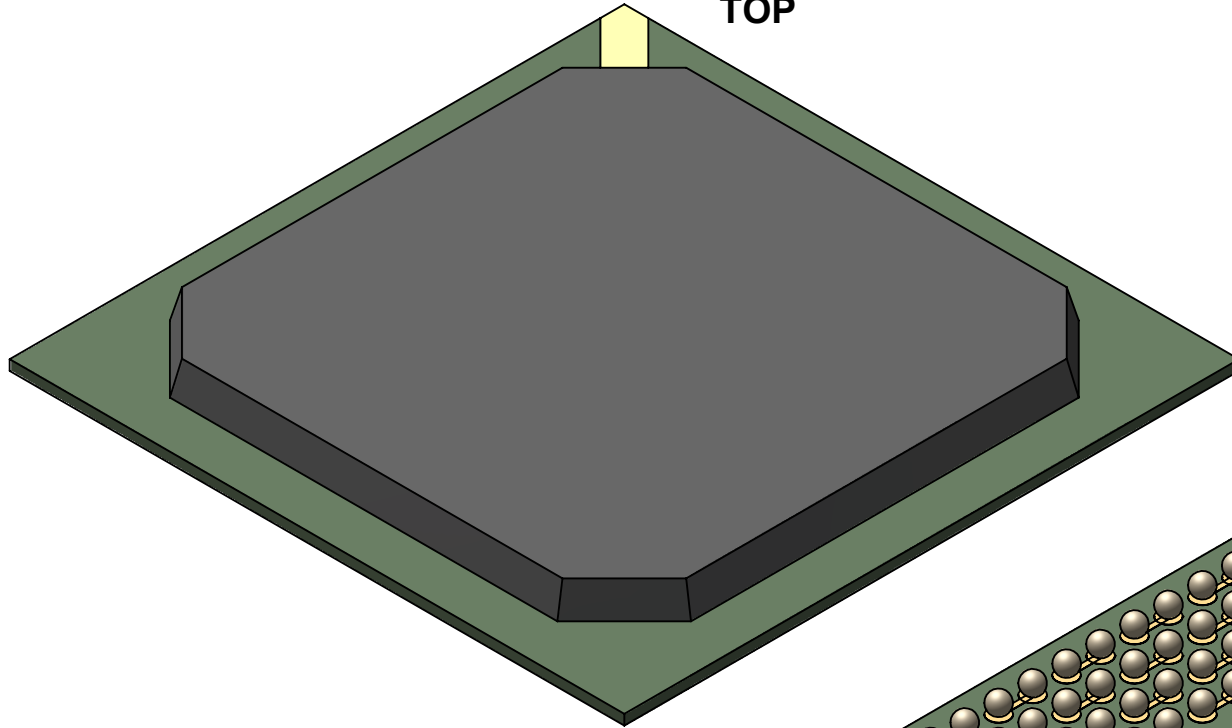
- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.762 (30 MIL).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.50 (20 MIL).
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING: 0.635 (25 MIL).



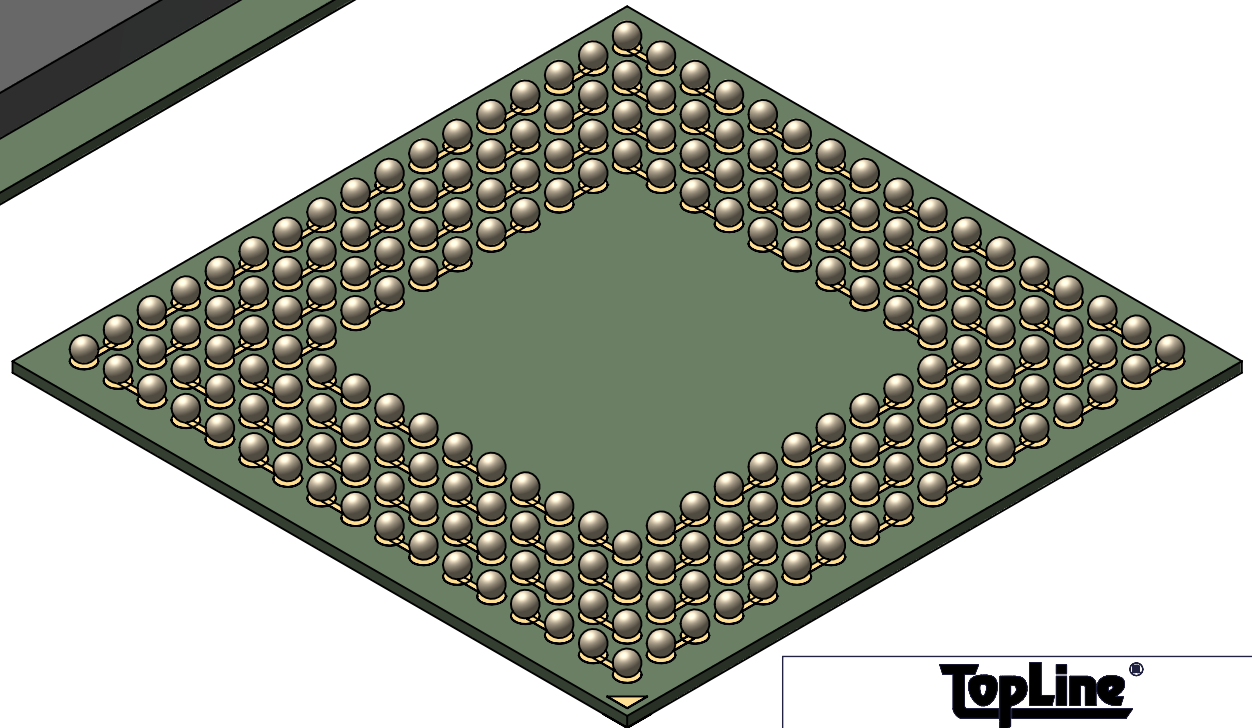
TITLE			
BGA208T1.27C-DC170D DAISY CHAIN DUMMY			
SCALE	SIZE	DRAWING NO.	REV
2.5:1	A	521704	A
DO NOT SCALE DRAWING			SHEET 2 OF 3

MODEL

TOP



BOTTOM



TopLine[®]

TITLE BGA208T1.27C-DC170D
DAISY CHAIN DUMMY

SCALE 2.5:1	SIZE A	DRAWING NO. 521704	REV A
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DO NOT SCALE DRAWING

SHEET 3 OF 3